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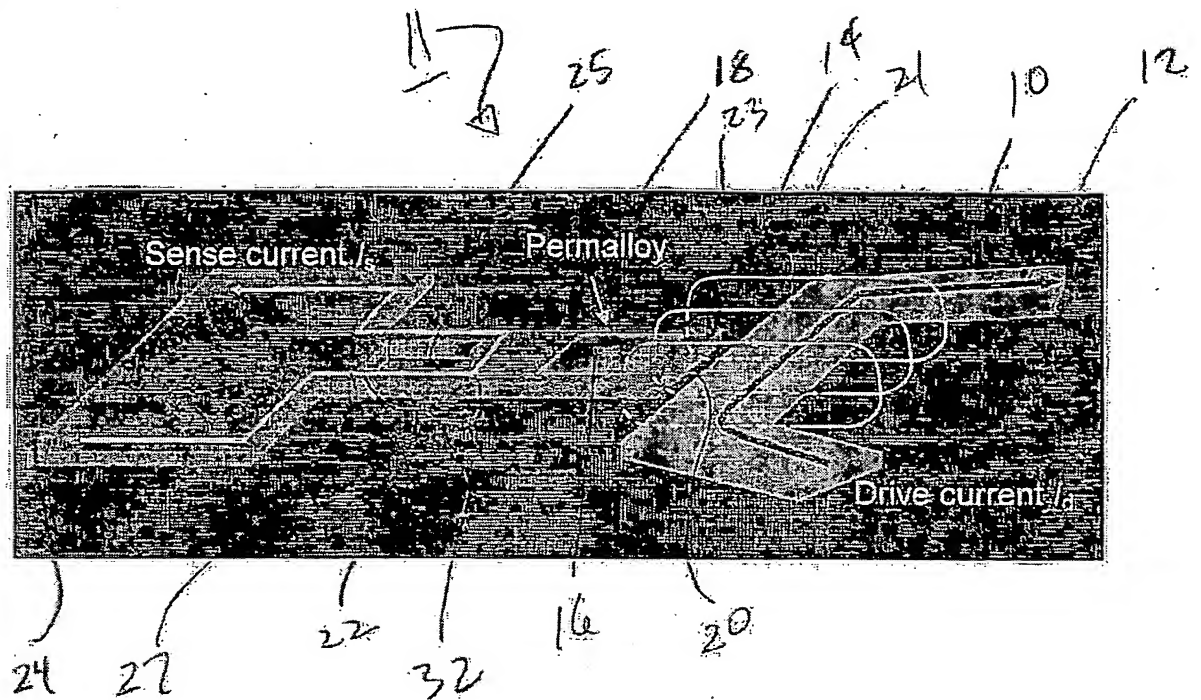
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Fig. 1



F15.2

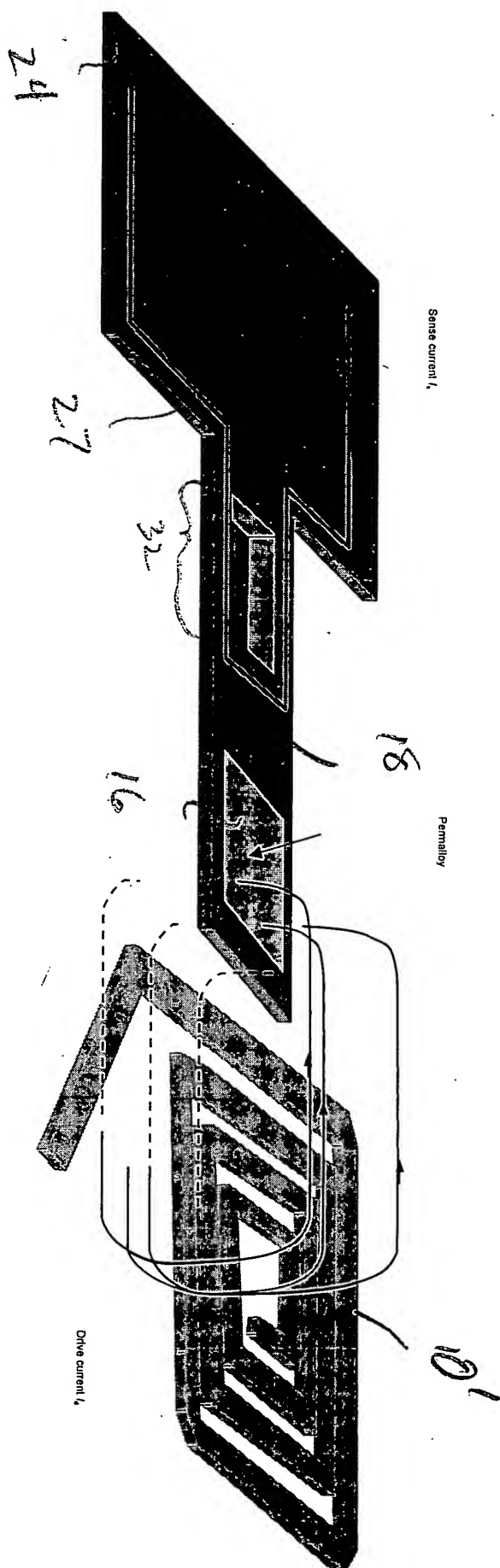


Fig. B

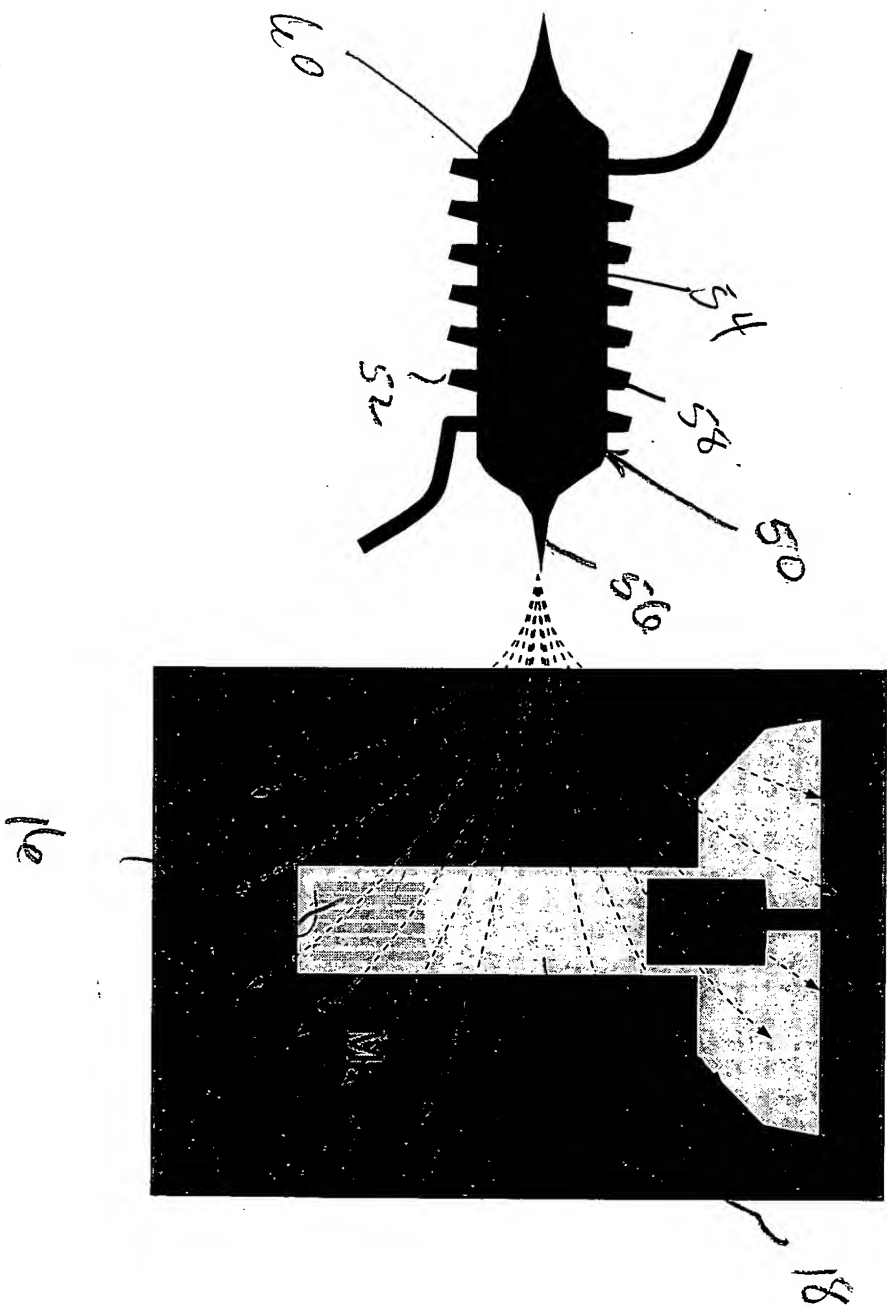


Fig. 4(a)

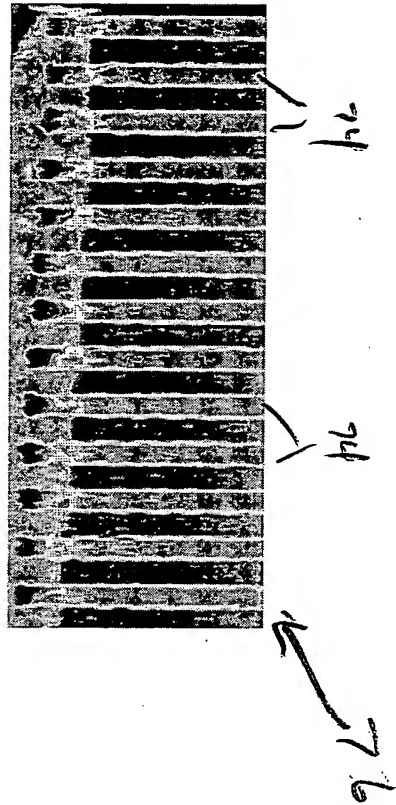
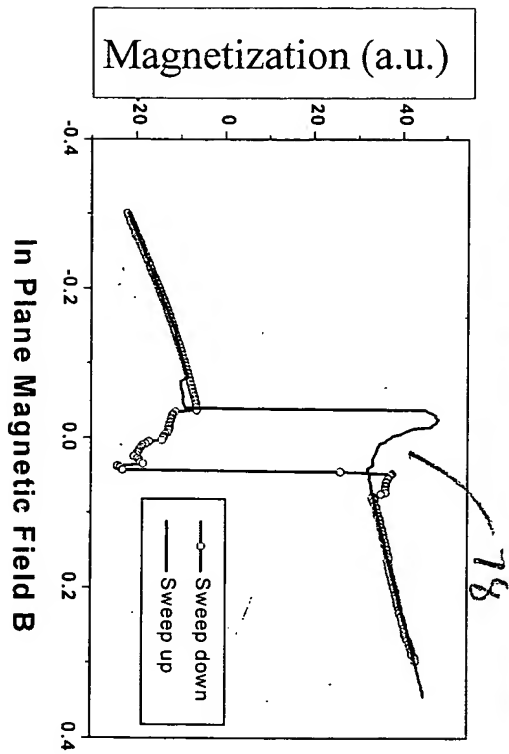
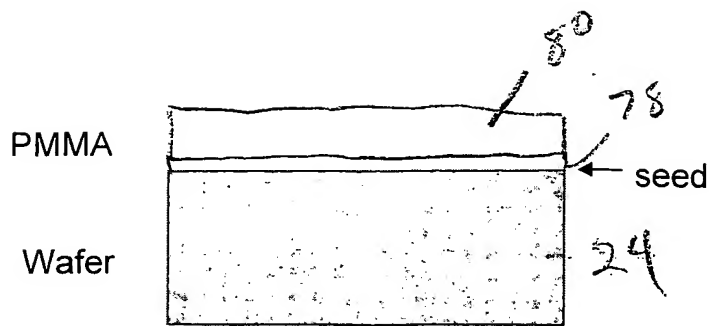
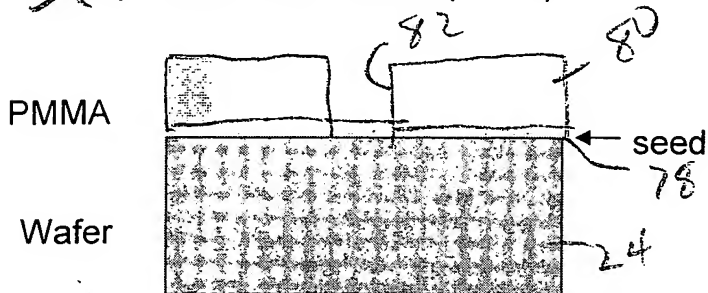


Fig. 4(b)

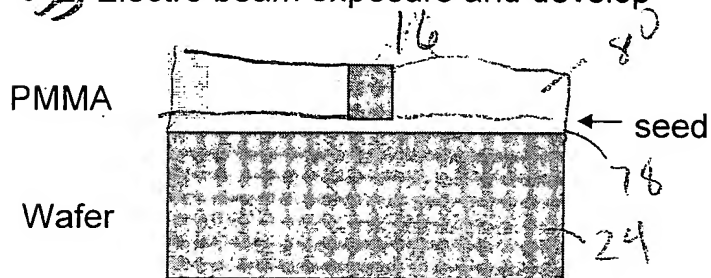




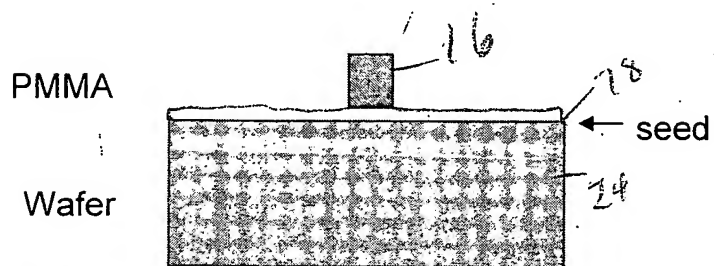
51 Spin coat thick PMMA (~2um)



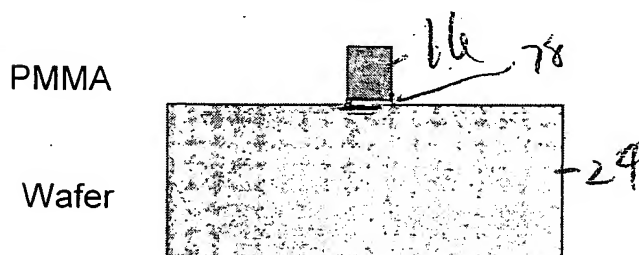
52 Electro beam exposure and develop



53 Electro beam exposure and develop



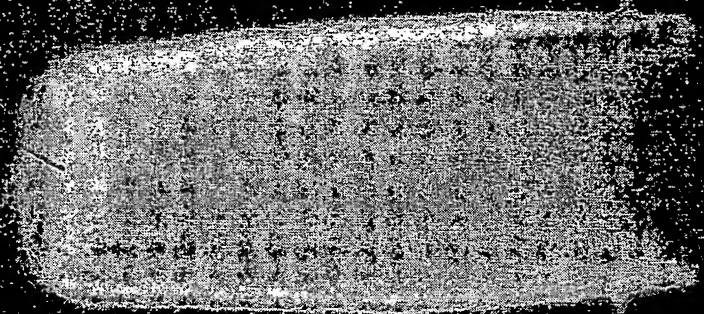
54 Stripe off PMMA



55 Dry etch seed metal layer

Fig. 5f

16



CIT 40KV X20,000 45mm 12m

Fig. 6a



Cu or coating 30 nm

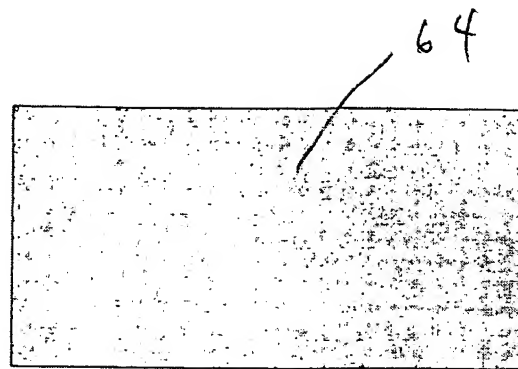
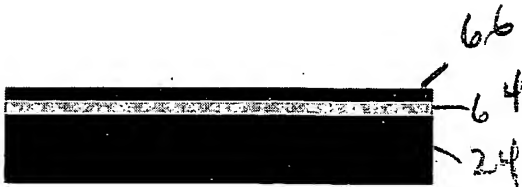


Fig. 6b



Insulator deposition 1um
SiN or cured photoresist

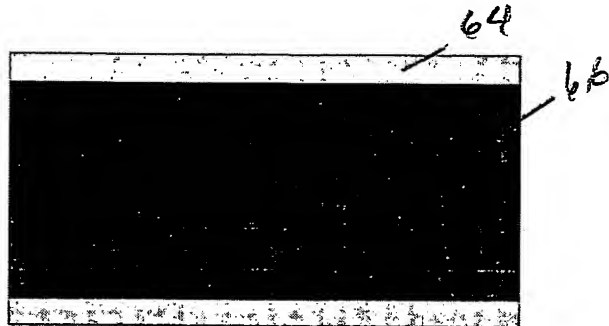
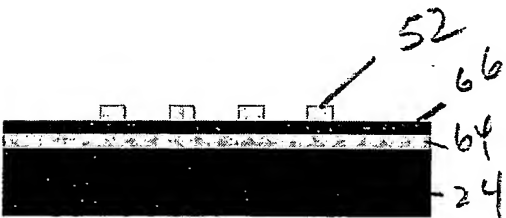


Fig. 6c



Bottom conductor
Plating, Cu or Au 1um

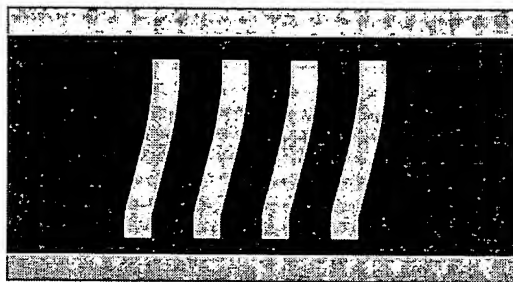
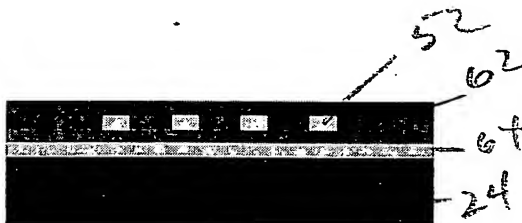


Fig. 6d



1um Cured Photoresist
Or PECVD SiO2

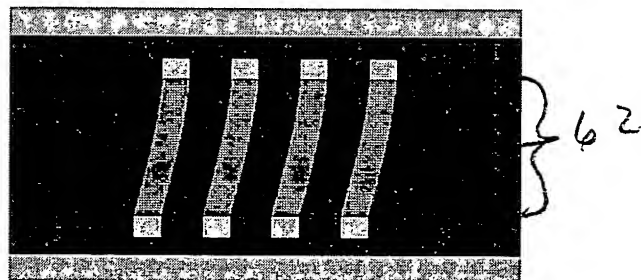
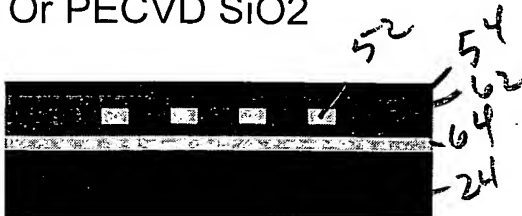


Fig. 6e



Electroplate 1um Ni core

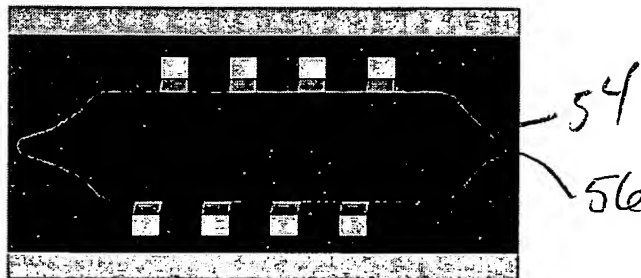
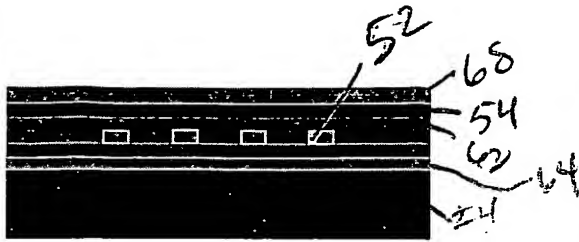


Fig. 6f



1um cured Photoresist
Or PECVD SiO₂

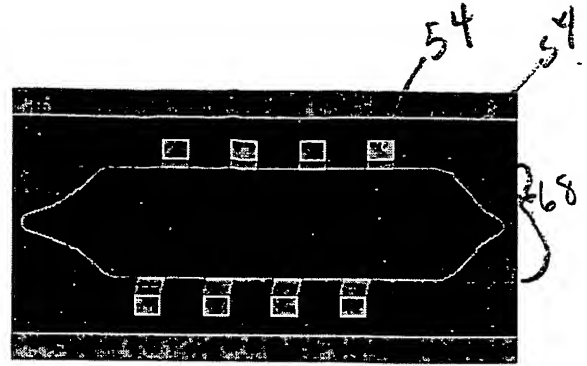
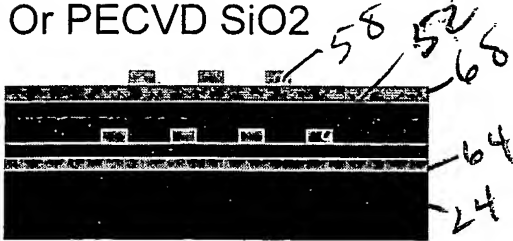


Fig. 6g



Electroplate Cu or Au

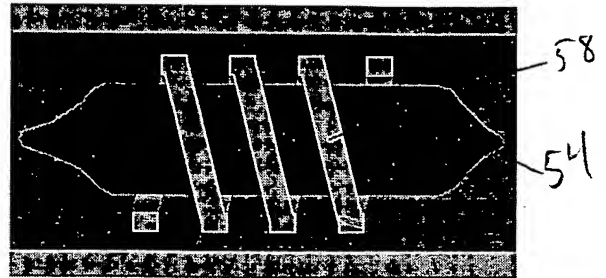
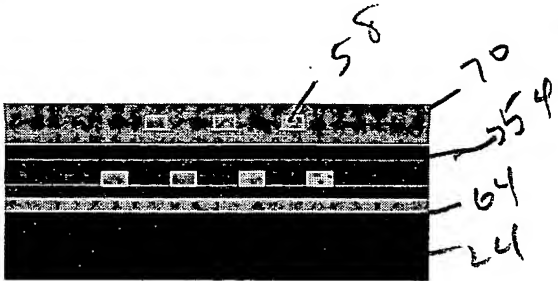


Fig. 6h



Cap Photoresist or SiO₂

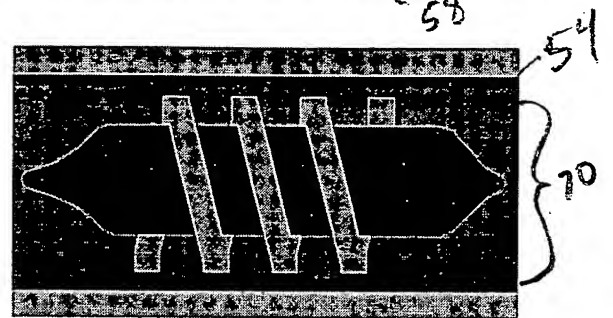
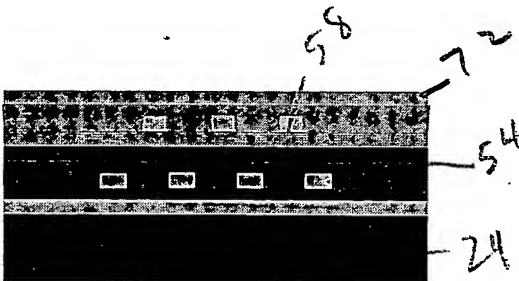


Fig. 6i



Cap with metal/SiN for electrical
shielding / passivation

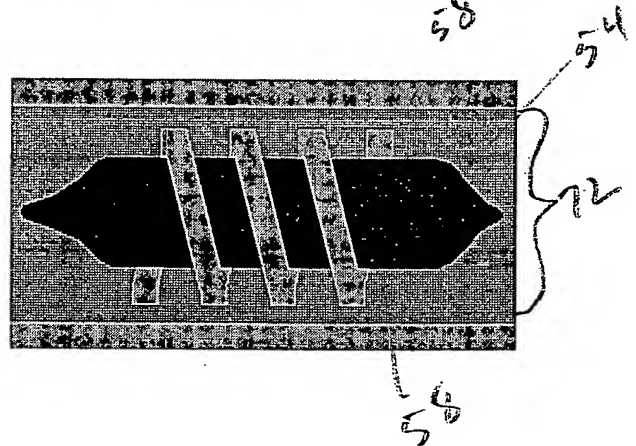


Fig. 7

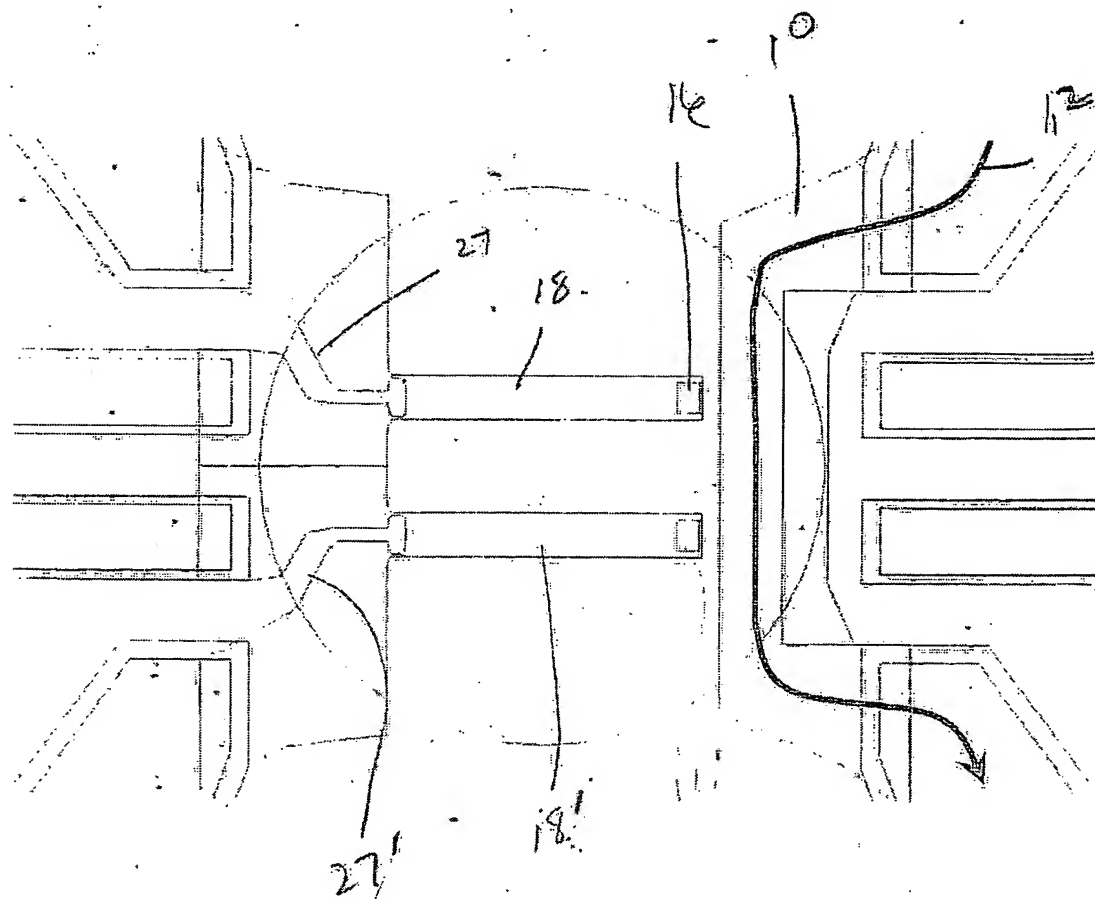


Fig. 8

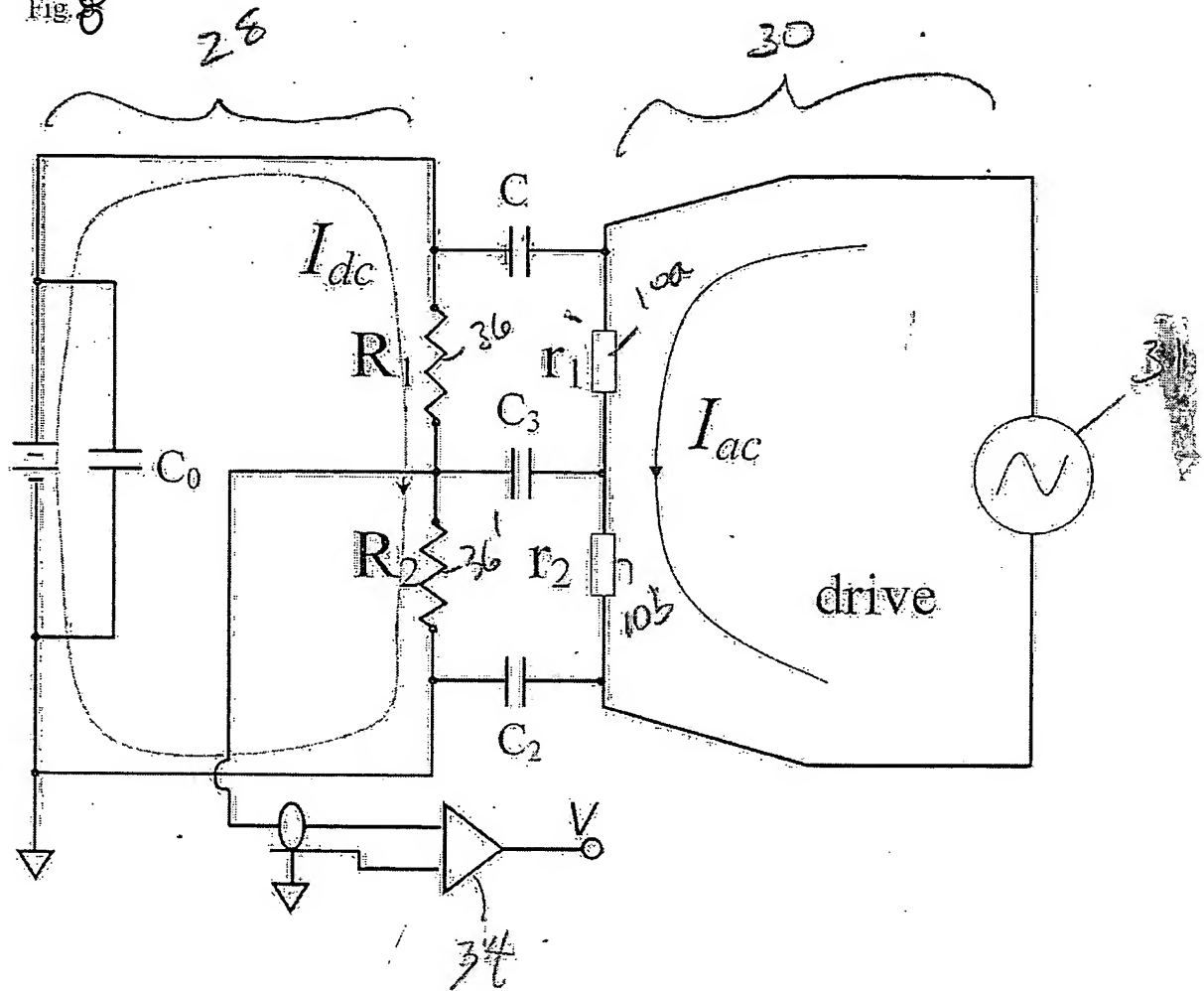


Fig. 7a

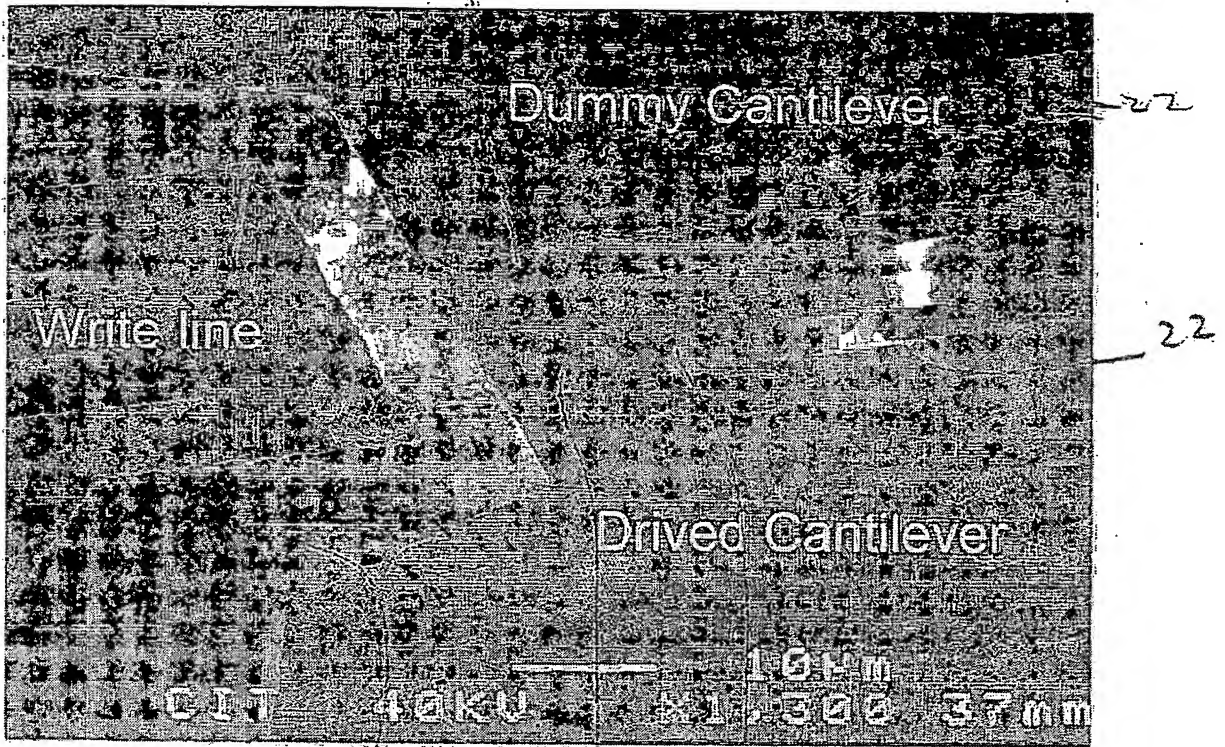


Fig. 9b

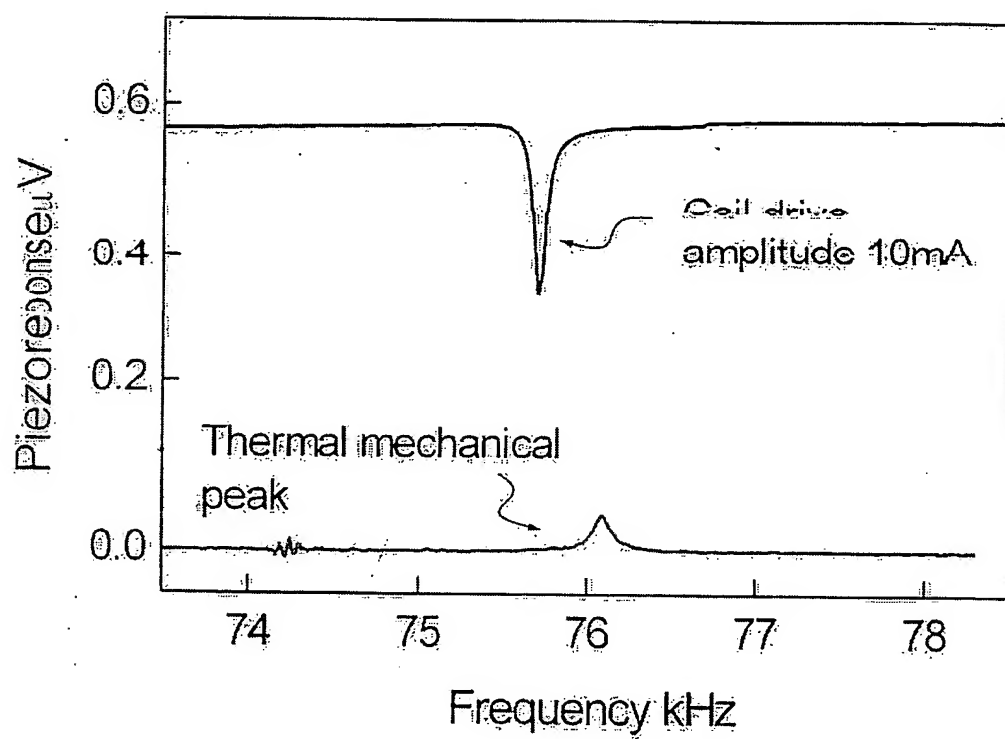


Fig. 10

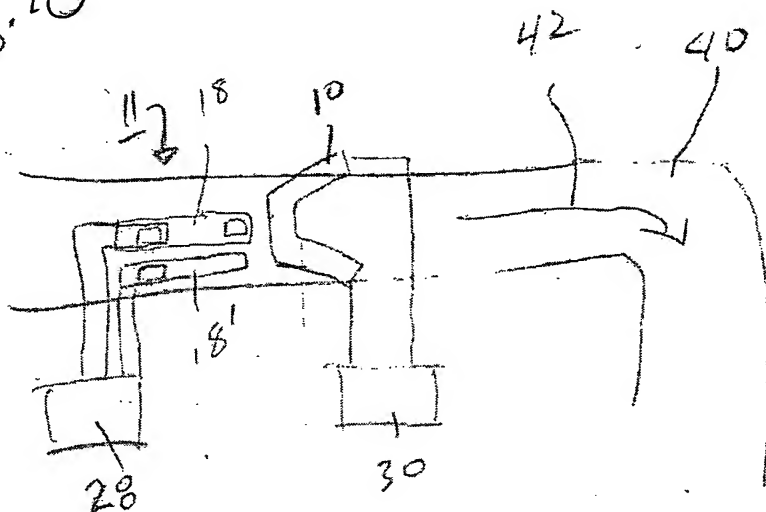


Fig. 11

